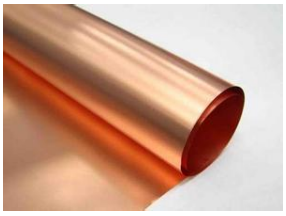
曜田精密科技股份有限公司
Sunfield Technology Co., Ltd

Make the Difference

High Efficiency Heat Diffusion Foil

Product Description

The CB*** has a better thermal conductivity and mean temperature effective, it has good chemical stability and weather resistance, and can work under the environment of high temperature stability for a long time.



Features

- High mechanical strength, high toughness
- Good adhesion on thermal interface.
- No peeling issue.
- Easy radiation by far infra ray.
- Roll to Roll easy to mass production.

Applications

- Cellphone、Tablet、Notebook、PCB for Digital Camera、Chipset、LCD
- Router、Disk drive、GPS、Game Device
- Masking Device、Testing Equipment、Military electronics

Storage and Shelf Life

- Best recommended validity: Within less than 6 months.
- Best recommended storage condition: Temperature (25°C~30°C) & Humidity (50%RH~60%RH)
- The measuring data was determined under the laboratory condition, and can be used as a reference only.
- Performance may vary when using in different applications.
- Less of silicone fluid may exude from the product when using in certain operating conditions.

SPECIFICATION

Item	Condition	Unit	Test method	Thickness(μm) 9,12,18,35,70,105	Test frequency
Copper foil properties					
Thermal conductivity	XYZ axis	W/mk	AC calorimeter	380	-
Purity	A	%	IPC-TM-650	≧99.8	C
Resistivity	at 20°C	Ω-g/m	IPC-TM-650	≦0.162	C
Area weight	A	g/ m²	IPC-TM-650	583	A
Tensile Strength	A	kg/mm²	IPC-TM-650	34	A
	at 180°C*5Min.	kg/mm²	IPC-TM-650	25	A
Elongation	A	%	IPC-TM-650	25	A
	at 180°C*5Min.	%	IPC-TM-650	15	A
S/S Ra	A	μm	IPC-TM-650	0.25	A
M/S Rz	A	μm	IPC-TM-650	11.5	A
Copper powder test	A	grade	NAN YA standard(Q05)	≦1-2	A
Pinholes	A	—	CCD	ND	A
Oxidation	200°C* 60Min.	—	NAN YA standard(Q07)	PASS	A
CCL properties					
Peel Strength	A	lb/in	IPC-TM-650	18	A
	S-4	lb/in	IPC-TM-650	18	A
Solder ability	288°C	—	IPC-TM-650	Wetting	A
Solder blister	288°C	sec	IPC-TM-650	≧120	A
Thermal baking test	190°C*2hr	—	IPC-TM-650	PASS	B